

#### **Overview**

The low ESR, surge-robust T510 is designed for demanding applications that require high surge current and high ripple current capability. This series builds upon the proven capabilities of our industrial grade tantalum chip capacitors to offer several advantages such as low ESR, high ripple current capability, excellent capacitance stability, and improved resistance to high in-rush currents. These benefits are achieved though the utilization of multiple anodes as well as high-stress, low impedance electrical conditioning performed prior to screening. This series is classified as MSL (Moisture Sensitivity Level) 1 under J STD 020: unlimited floor life time at  $\leq$  30°C/85% RH.

#### **Benefits**

- Meets or exceeds EIA Standard 535BAAC
- Taped and reeled per EIA 481
- · High surge current capability
- Optional gold-plated terminations
- High ripple current capability
- 100% surge current test
- 100% steady-state accelerated aging
- Case sizes E and X
- + ESR as low as 10  $m\Omega$



# **Applications**

Typical applications include decoupling and filtering in many end applications, such as DC/DC converters, portable electronics, telecommunications, and control units requiring high ripple current capability.

# **Environmental Compliance**

RoHS compliant (6/6) according to Directive 2002/95/EC when ordered with 100% Sn solder or gold-plated.

- Halogen-free
- Epoxy compliant with UL94 V-0
- Molded Epoxy complies for outgassing testing under ASTM E 595.



#### K-SIM

For a detailed analysis of specific part numbers, please visit ksim.kemet.com to access KEMET's K-SIM software. KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels.

#### **Ordering Information**

Т	510	X	477	Μ	006	Α	т	E800	
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VDC)	Failure Rate/ Design	Termination Finish	ESR	Packaging (C-Spec)
T = Tantalum	Multiple Anode Low ESR	E X	First two digits represent significant figures. Third digit specifies number of zeros.	K = ±10% M = ±20%	004 = 4 006 = 6.3 010 = 10 016 = 16 020 = 20 025 = 25 035 = 35 050 = 50	A = N/A Z = N/A	T = 100% Matte Tin (Sn) Plated H = Standard Solder Coated (SnPb 5% Pb minimum) G = Gold Plated (A, B, C, D, X only)	Last three digits specify ESR in mΩ. (800 = 800 mΩ)	Blank = 7" Reel 7280 = 13" Reel

#### **Performance Characteristics**

Item	Performance Characteristics
Operating Temperature	-55°C to 125°C
Rated Capacitance Range	10 – 1,000 μF at 120 Hz/25°C
Capacitance Tolerance	K Tolerance (10%), M Tolerance (20%)
Rated Voltage Range	4 – 50 V
DF (120 Hz)	Refer to Part Number Electrical Specification Table
ESR (100 kHz)	Refer to Part Number Electrical Specification Table
Leakage Current	$\leq$ 0.01 CV (µA) at rated voltage after 5 minutes



# Qualification

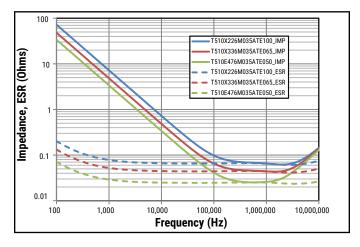
Test	Condition			Charact	teristics				
			ΔC/C	Within ±10%	6 of initial valu	е			
Endurance	85°C at rated voltage, 2,000 hours	DF	Within initial limits						
Endurance	125°C at 2/3 rated voltage, 2,000 hours	DCL	Within 1.25	x initial limit					
		ESR	Within initia	al limits					
			ΔC/C	Within ±10%	6 of initial valu	е			
Otomore Life		DF	Within initia	al limits					
Storage Life	125°C @ 0 volts, 2,000 hours		DCL	Within 1.25	x initial limit				
			ESR	Within initial limits					
			∆C/C	Within ±5% of initial value					
	MIL-STD-202, Method 107, Condition B, mo	DF	Within initia	al limits					
Thermal Shock	-55C° to 125° C, 1,000 cycles	DCL	Within 1.25	x initial limit					
		ESR	Within initia	al limits					
			+25°C	-55°C	+85°C	+125°C			
Tama anatura Otahilitu	Extreme temperature exposure at a	ΔC/C	IL*	±10%	±10%	±20%			
Temperature Stability	succession of continuous steps at +25°C, -55°C, +25°C, +85°C, +125°C, +25°C	DF	IL	IL	1.5 x IL	1.5 x IL			
		DCL	IL	n/a	10 x IL	12 x IL			
			ΔC/C	Within ±5%	of initial value				
Curre Maltare	85°C, 1.32 x rated voltage 1,000 cycles		DF	Within initia	al limits				
Surge Voltage	(125°C, 1.2 x rated voltage)		DCL	Within initial limits					
						Within initial limits			
	MIL-STD-202, Method 213, Condition I, 100	Gneak	ΔC/C	Within ±10% of initial value					
Mechanical Shock/ Vibration	MIL-STD-202, Method 204, Condition D, 10	•	DF	Within initia	Within initial limits				
	2,000 Hz, 20 G peak		DCL	Within initial limits					

\*IL = Initial limit



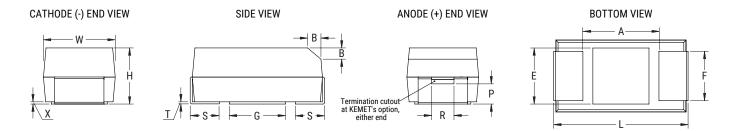
# **Electrical Characteristics**

Impedance, ESR vs. Frequency



#### **Dimensions – Millimeters (Inches)**

Metric will govern



100

Capacitance (µF)

10

100

1,000

Case	Size		Component									Total Weight			
KEMET	EIA	L	W	Н	F ±0.1 ±(.004)	S ±0.3 ±(.012)	B ±0.15 (Ref) ±.006	X (Ref)	P (Ref)	R (Ref)	T (Ref)	A (Min)	G (Ref)	E (Ref)	(mg)
Х	7343-43	7.3 ±0.3 (0.287 ±0.012)	4.3 ±0.3 (0.169 ±0.012)	4.0 ±0.3 (0.157 ±0.012)	2.4 (0.094)	1.3 (0.051)	0.5 (0.020)	0.10 ±0.10 (0.004 ±0.004)	1.7 (0.067)	1.0 (0.039)	0.13 (0.005)	3.8 (0.150)	3.5 (0.138)	3.5 (0.138)	430.15
E	7360-38	7.3 ±0.3 (0.287 ±0.012)	6.0 ±0.3 (0.236 ±0.012)	3.6 ±0.2 (0.142 ±0.008)	4.1 (0.161)	1.3 (0.051)	0.5 (0.020)	0.10±0.10 (0.004±0.004)	n/a	n/a	0.13 (0.005)	3.8 (0.150)	3.5 (0.138)	3.5 (0.138)	500.73

Notes: (Ref) – Dimensions provided for reference only. For low profile cases, no dimensions are provided for B, P or R because these cases do not have a bevel or a notch.

These weights are provided as reference. If exact weights are needed, please contact your KEMET Sales Representative

#### Capacitance vs. Frequency

T510X226M035ATE100 T510X336M035ATE065

T510E476M035ATE050

Frequency (Hz)

100,000

1,000,000

10,000,000

10,000



#### Table 1 – Ratings & Part Number Reference

Rated Voltage	Rated Cap	Case Code/ Case Size	KEMET Part Number	DC Leakage	DF	ESR	-	mum Allo le Current		Maximum Operating Temp	MSL
VDC at 85°C	μF	KEMET/EIA	(See below for part options)	µA at +25°C Max/5 Min	% at +25°C 120 Hz Max	mΩ at 25°C 100 kHz Max	mA at +25°C 100 kHz	mA at +85°C 100 kHz	mA at +125°C 100 kHz	°C	Reflow Temp ≤ 260°C
4	680	X/7343-43	T510X687(1)004A(2)E030	27.2	6.0	30	3000	2700	1200	125	1
4	1000	X/7343-43	T510X108(1)004A(2)E018	40.0	6.0	18	3873	3486	1549	125	1
4	1000	X/7343-43	T510X108(1)004A(2)E023	40.0	6.0	23	3426	3083	1370	125	1
4	1000	X/7343-43	T510X108(1)004A(2)E030	40.0	6.0	30	3000	2700	1200	125	1
4	1000	X/7343-43	T510X108(1)004A(2)E035	40.0	6.0	35	2777	2499	1111	125	1
4	1000	E/7360-38	T510E108(1)004A(2)E018	40.0	6.0	18	3979	3581	1592	125	1
4	1000	E/7360-38	T510E108(1)004A(2)E010	40.0	6.0	10	5339	4805	2136	125	1
6.3	470	X/7343-43	T510X477(1)006A(2)E030	29.6	6.0	30	3000	2700	1200	125	1
6.3	680	X/7343-43	T510X687(1)006A(2)E023	42.8	6.0	23	3426	3083	1370	125	1
6.3	680	X/7343-43	T510X687(1)006A(2)E045	42.8	12.0	45	2449	2204	980	125	1
6.3	680	E/7360-38	T510E687(1)006A(2)E023	42.8	6.0	23	3520	3168	1408	125	1
6.3	680	E/7360-38	T510E687(1)006A(2)E012	42.8	6.0	12	4873	4386	1949	125	1
10	330	X/7343-43	T510X337(1)010A(2)E035	33.0	6.0	35	2777	2499	1111	125	1
16	150	X/7343-43	T510X157(1)016A(2)E030	24.0	6.0	30	3000	2700	1200	125	1
16	150	X/7343-43	T510X157(1)016A(2)E040	24.0	6.0	40	2598	2338	1039	125	1
16	220	X/7343-43	T510X227(1)016A(2)E040	35.2	10.0	40	2598	2338	1039	125	1
16	220	X/7343-43	T510X227(1)016A(2)E025	35.2	10.0	25	3286	2957	1314	125	1
20	68	X/7343-43	T510X686(1)020A(2)E055	14.0	6.0	55	2216	1994	886	125	1
20	68	X/7343-43	T510X686(1)020A(2)E045	14.0	6.0	45	2449	2204	980	125	1
20	100	X/7343-43	T510X107(1)020A(2)E035	20.0	8.0	35	2777	2499	1111	125	1
20	100	X/7343-43	T510X107(1)020A(2)E040	20.0	6.0	40	2598	2338	1039	125	1
20	100	X/7343-43	T510X107(1)020A(2)E045	20.0	6.0	45	2449	2204	980	125	1
20	100	X/7343-43	T510X107(1)020A(2)E055	20.0	6.0	55	2216	1994	886	125	1
25	68	X/7343-43	T510X686(1)025A(2)E045	17.0	8.0	45	2449	2204	980	125	1
25	100	E/7360-38	T510E107(1)025A(2)E050	25.0	8.0	50	2387	2148	955	125	1
35	22	X/7343-43	T510X226(1)035A(2)E100	7.7	6.0	100	1643	1479	657	125	1
35	22	X/7343-43	T510X226(1)035A(2)E080	7.7	6.0	80	1837	1653	735	125	1
35	22	X/7343-43	T510X226(1)035A(2)E060	7.7	6.0	60	2121	1909	848	125	1
35	33	X/7343-43	T510X336(1)035A(2)E065	11.6	6.0	65	2038	1834	815	125	1
35	33	X/7343-43	T510X336(1)035A(2)E050	11.6	6.0	50	2324	2092	930	125	1
35	47	X/7343-43	T510X476(1)035A(2)E055	16.5	8.0	55	2216	1994	886	125	1
35	47	X/7343-43	T510X476(1)035A(2)E065	16.5	8.0	65	2038	1834	815	125	1
35	47	E/7360-38	T510E476(1)035A(2)E050	16.5	8.0	50	2387	2148	955	125	1
50	10	X/7343-43	T510X106(1)050A(2)E120	5.0	8.0	120	1500	1350	600	125	1
50	10	X/7343-43	T510X106(1)050A(2)E090	5.0	8.0	90	1732	1559	693	125	1
50	22	X/7343-43	T510X226(1)050A(2)E100	11.0	8.0	100	1643	1479	657	125	1
50	22	X/7343-43	T510X226(1)050A(2)E075	11.0	8.0	75	1897	1707	759	125	1
VDC at 85°C	μF	KEMET/EIA	(See below for part options)	µA at +25°C Max/5 Min	% at +25°C 120 Hz Max	mΩ at 25°C 100 kHz Max	mA at +25°C 100 kHz	mA at +85°C 100 kHz	mA at +125°C 100 kHz	°C	Reflow Temp ≤ 260°C
Rated Voltage	Rated Cap	Case Code/ Case Size	KEMET Part Number	DC Leakage	DF	ESR		ximum Allow ple Current (		Maximum Operating Temp	MSL

(1) To complete KEMET part number, insert M for ±20% or K for ±10%. Designates Capacitance tolerance.

(2) To complete KEMET part number, insert T = 100% Matte Tin (Sn) Plated, G = Gold Plated, H = Standard Solder coated (SnPb 5% Pb minimum). Designates Termination Finish.

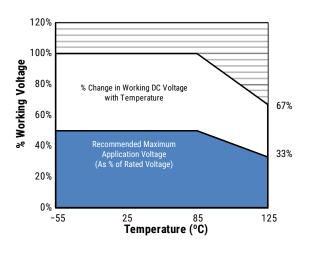
Refer to Ordering Information for additional detail.

Higher voltage ratings and tighter tolerance product including ESR may be substituted within the same size at KEMET's option. Voltage substitution will be marked with the higher voltage rating. Substitutions can include better than series.



# **Recommended Voltage Derating Guidelines**

	-55°C to 85°C	85°C to 125°C
% Change in Working DC Voltage with Temperature	V <sub>R</sub>	67% of V <sub>R</sub>
Recommended Maximum Application Voltage	50% of $V_{_{\rm R}}$	33% of V <sub>R</sub>



# **Ripple Current/Ripple Voltage**

Permissible AC ripple voltage and current are related to equivalent series resistance (ESR) and the power dissipation capabilities of the device. Permissible AC ripple voltage which may be applied is limited by two criteria:

1. The positive peak AC voltage plus the DC bias voltage, if any, must not exceed the DC voltage rating of the capacitor.

2. The negative peak AC voltage in combination with bias voltage, if any, must not exceed the allowable limits specified for reverse voltage. See the Reverse Voltage section for allowable limits.

The maximum power dissipation by case size can be determined using the table at right. The maximum power dissipation rating stated in the table must be reduced with increasing environmental operating temperatures. Refer to the table below for temperature compensation requirements.

Temperature Compensation Multipliers for Maximum Ripple Current							
T ≤ 25°C	T ≤ 85°C	T ≤ 125°C					
1.00 0.90 0.40							

*T* = *Environmental Temperature* 

The maximum power dissipation rating must be reduced with increasing environmental operating temperatures. Refer to the Temperature Compensation Multiplier table for details.

KEMET Case Code	EIA Case Code	Maximum Power Dissipation (P max) mWatts @ 25°C w/+20°C Rise
А	3216-18	75
В	3528-21	85
С	6032-28	110
D	7343-31	150
Х	7343-43	165
E	7360-38	200
S	3216-12	60
Т	3528-12	70
U	6032-15	90
V	7343-20	125
T510X	7343-43	270
T510E	7360-38	285

Using the P max of the device, the maximum allowable rms ripple current or voltage may be determined.

 $I(max) = \sqrt{P max/R}$  $E(max) = Z \sqrt{P max/R}$ 

*I = rms ripple current (amperes)* 

*E* = *rms ripple voltage* (*volts*)

P max = maximum power dissipation (watts)

R = ESR at specified frequency (ohms)

Z = Impedance at specified frequency (ohms)



#### **Reverse Voltage**

Solid tantalum capacitors are polar devices and may be permanently damaged or destroyed if connected with the wrong polarity. The positive terminal is identified on the capacitor body by a stripe plus in some cases a beveled edge. A small degree of transient reverse voltage is permissible for short periods per the table. The capacitors should not be operated continuously in reverse mode, even within these limits.

Temperature	Permissible Transient Reverse Voltage
25°C	15% of Rated Voltage
85°C	5% of Rated Voltage
125°C	1% of Rated Voltage

#### Table 2 – Land Dimensions/Courtyard

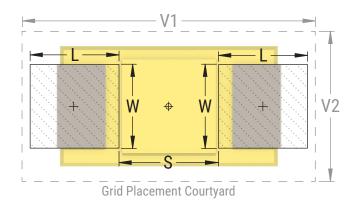
KEMET	Metric Size Code	Density Level A: Maximum (Most) Land Protrusion (mm)			Density Level B: Median (Nominal) Land Protrusion (mm)					Density Level C: Minimum (Least) Land Protrusion (mm)						
Case	EIA	W	W L S V1 V2			W	L	S	V1	V2	W	L	S	V1	V2	
E1	7360-38	4.25	2.77	3.67	10.22	7.30	4.13	2.37	3.87	9.12	6.80	4.03	1.99	4.03	8.26	6.54
<b>X</b> <sup>1</sup>	7343-43	2.55	2.77	3.67	10.22	5.60	2.43	2.37	3.87	9.12	5.10	2.33	1.99	4.03	8.26	4.84

**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes. **Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC standard 7351 (IPC–7351).

<sup>1</sup> Height of these chips may create problems in wave soldering.

<sup>2</sup> Land pattern geometry is too small for silkscreen outline.





### Soldering Process

KEMET's families of surface mount capacitors are compatible with wave (single or dual), convection, IR, or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020D standard for moisture sensitivity testing. The devices can safely withstand a maximum of three reflow passes at these conditions.

Please note that although the X/7343-43 case size can withstand wave soldering, the tall profile (4.3 mm maximum) dictates care in wave process development.

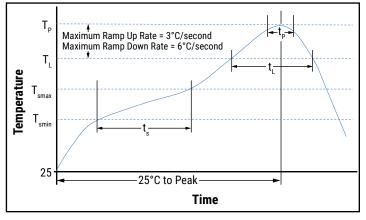
Hand soldering should be performed with care due to the difficulty in process control. If performed, care should be taken to avoid contact of the soldering iron to the molded case. The iron should be used to heat the solder pad, applying solder between the pad and the termination, until reflow occurs. Once reflow occurs, the iron should be removed immediately. "Wiping" the edges of a chip and heating the top surface is not recommended.

During typical reflow operations, a slight darkening of the gold-colored epoxy may be observed. This slight darkening is normal and not harmful to the product. Marking permanency is not affected by this change.

Profile Feature	SnPb Assembly	<b>Pb-Free Assembly</b>		
Preheat/Soak				
Temperature Minimum (T <sub>Smin</sub> )	100°C	150°C		
Temperature Maximum (T <sub>Smax</sub> )	150°C	200°C		
Time ( $t_s$ ) from $T_{min}$ to $T_{max}$ )	60 – 120 seconds	60 – 120 seconds		
Ramp-up Rate ( $T_L$ to $T_P$ )	3°C/second maximum	3°C/second maximum		
Liquidous Temperature (T <sub>L</sub> )	183°C	217°C		
Time Above Liquidous (t <sub>L</sub> )	60 – 150 seconds	60 – 150 seconds		
Peak Temperature (T <sub>P</sub> )	220°C* 235°C**	250°C* 260°C**		
Time within 5°C of Maximum Peak Temperature (t <sub>P</sub> )	20 seconds maximum	30 seconds maximum		
Ramp-down Rate $(T_{P} to T_{L})$	6°C/second maximum	6°C/second maximum		
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum		

Note: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow. \* For Case Size height > 2.5 mm

\*\* For Case Size height ≤ 2.5 mm

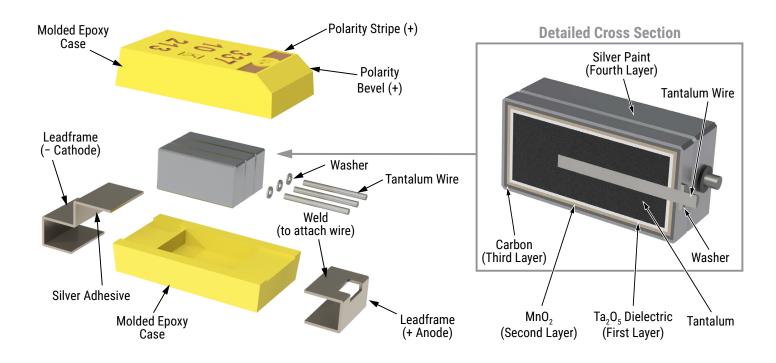


#### **Storage**

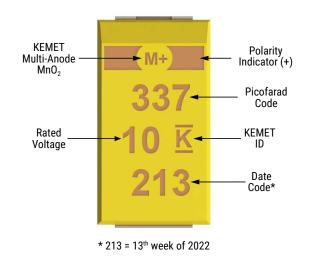
Tantalum chip capacitors should be stored in normal working environments. While the chips themselves are guite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature – reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 60% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulphur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within three years of receipt.



#### Construction



**Capacitor Marking** 

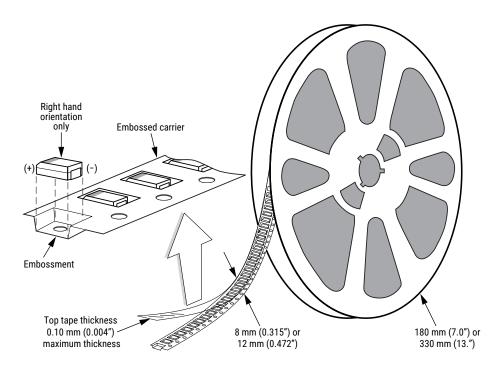


Date (	Code *
1 <sup>st</sup> digit = last number of year	8 = 2018 9 = 2019 0 = 2020 1 = 2021 2 = 2022
2 <sup>nd</sup> and 3 <sup>rd</sup> digit = week of the year	01 = $1^{st}$ week of the year to 52 = $52^{nd}$ week of the year



#### **Tape & Reel Packaging Information**

KEMET's molded chip capacitor families are packaged in 8 and 12 mm plastic tape on 7" and 13" reels in accordance with *EIA Standard 481*: Embossed Carrier Taping of Surface Mount Components for Automatic Handling. This packaging system is compatible with all tape-fed automatic pick-and-place systems.



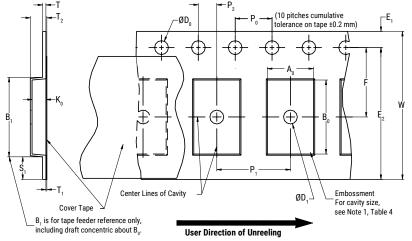
# Table 3 – Packaging Quantity

Case Code		Tape Width (mm)	7" Reel*	13" Reel*	
KEMET	EIA				
S	3216-12	8	2,500	10,000	
Т	3528-12	8	3,000	10,000	
М	3528-15	8	2,500	8,000	
U	6032-15	12	1,000	5,000	
L	6032-19	12	1,000	3,000	
W	7343-15	12	1,000	3,000	
Z	7343-17	12	1,000	3,000	
V	7343-20	12	1,000	3,000	
A	3216-18	8	2,000	9,000	
В	3528-21	8	2,000	8,000	
С	6032-28	12	500	3,000	
D	7343-31	12	500	2,500	
Q	7343-12	12	1,000	3,000	
Y	7343-40	12	500	2,000	
Х	7343-43	12	500	2,000	
E/T428P	7360-38	12	500	2,000	
Н	7360-20	12	1,000	2,500	
0	7360-43	12	250	1,000	

\* No C-Spec required for 7" reel packaging. C-7280 required for 13" reel packaging.



# Figure 1 – Embossed (Plastic) Carrier Tape Dimensions



# Table 4 – Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

	Constant Dimensions – Millimeters (Inches)									
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimum Note 1	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Reference Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum	
8 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.0 (0.039)	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	25.0 (0.984)	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)	
12 mm		1.5 (0.059)				30 (1.181)				

Variable Dimensions – Millimeters (Inches)									
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>	T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> , B <sub>0</sub> & K <sub>0</sub>	
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	2.0 ±0.05 or 4.0 ±0.10 (0.079 ±0.002 or 0.157 ±0.004)	2.5 (0.098)	8.3 (0.327)		
12 mm	Single (4 mm) and Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5 ±0.05 (0.217 ±0.002)	2.0 ±0.05 (0.079 ±0.002) or 4.0 ±0.10 (0.157 ±0.004) or 8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	12.3 (0.484)	Note 5	

1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.

2. The tape, with or without components, shall pass around R without damage (see Figure 4).

3. If  $S_1 < 1.0$  mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481–D, paragraph 4.3, section b).

4. B, dimension is a reference dimension for tape feeder clearance only.

5. The cavity defined by  $A_{\alpha}$ ,  $B_{\alpha}$  and  $K_{\alpha}$  shall surround the component with sufficient clearance that:

(a) the component does not protrude above the top surface of the carrier tape.

(b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.

(c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes (see Figure 2).

(d) lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape (see Figure 3).

(e) see Addendum in EIA Standard 481–D for standards relating to more precise taping requirements.



# **Packaging Information Performance Notes**

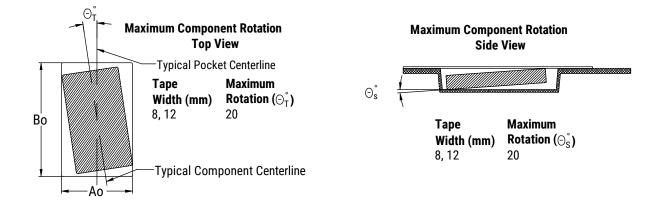
- 1. Cover tape break force: 1.0 kg minimum.
- 2. Cover tape peel strength: The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength		
8 mm	0.1 to 1.0 newton (10 to 100 gf)		
12 mm	0.1 to 1.3 newton (10 to 130 gf)		

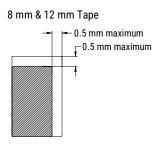
The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be  $165^{\circ}$  to  $180^{\circ}$  from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of  $300 \pm 10$  mm/minute.

**3. Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards 556 and 624*.

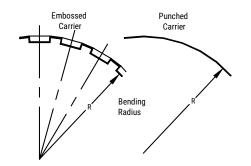
#### Figure 2 – Maximum Component Rotation



# Figure 3 – Maximum Lateral Movement

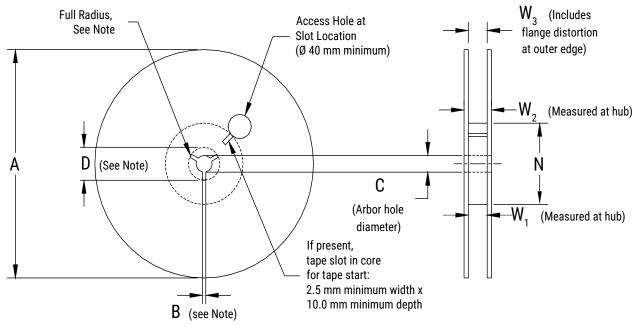


# Figure 4 – Bending Radius





# Figure 5 – Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

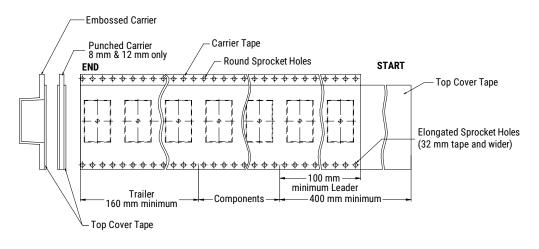
# Table 5 – Reel Dimensions

Metric will govern

	Constant Dimensions — Millimeters (Inches)								
Tape Size	А	B Minimum	С	D Minimum					
8 mm	178 ±0.20 (7.008 ±0.008)			20.2 (0.795)					
12 mm	or 330 ±0.20 (13.000 ±0.008)	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)						
	Variable Dimensions – Millimeters (Inches)								
Tape Size	N Minimum	W <sub>1</sub>	W <sub>2</sub> Maximum	W <sub>3</sub>					
8 mm	50	8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)	Shall accommodate tape					
12 mm	(1.969)	12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	width without interference					



# Figure 6 – Tape Leader & Trailer Dimensions



# Figure 7 – Maximum Camber





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